

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	("5762749").PN:	US-PGPUB; USPAT; USOCR	OR	OFF	2005/05/31 11:03
S1	3	c23c016\$.ipc. and (dry\$3 with heat\$3 with compress\$3 with air)	US-PGPUB; USPAT	OR	ON	2004/09/29 16:54
S2	1	c23c016\$.ipc. and (dry\$3 with heat\$3 with compress\$3 with air)	EPO; JPO; DERWENT	OR	ON	2004/09/29 16:55
S3	10	"118"/\$.ccls. and (dry\$3 with heat\$3 with compress\$3 with air)	US-PGPUB; USPAT	OR	ON	2004/09/29 16:55
S4	5	(wafer substrate workpiece semiconductor) and (clean\$3 wash\$3) and (dry\$3 with heat\$3 with compress\$3 with air)	EPO; JPO; DERWENT	OR	ON	2004/09/29 16:55
S5	5	(wafer substrate workpiece semiconductor) and (clean\$3 wash\$3) and (dry\$3 with heat\$3 with compress\$3 with air)	EPO; JPO; DERWENT	OR	ON	2004/09/29 16:58
S6	97	(wafer substrate workpiece semiconductor) and (clean\$3 wash\$3) and (dry\$3 with heat\$3 with compress\$3 with air)	US-PGPUB; USPAT	OR	ON	2004/09/29 16:56
S7	11	(wafer substrate workpiece semiconductor) same (clean\$3 wash\$3) same (dry\$3 with heat\$3 with compress\$3 with air)	US-PGPUB; USPAT	OR	ON	2004/09/29 16:56
S8	1775	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/05/31 11:03
S9	289	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and ((wash\$3 clean\$3) same (dry\$3 heat\$3) same (etch\$3 deposit\$3 coat\$3))	US-PGPUB; USPAT	OR	ON	2003/09/26 16:18
S10	25	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and ((wash\$3 clean\$3) same (dry\$3 heat\$3) same (etch\$3 deposit\$3 coat\$3)) and 118/718.ccls.	US-PGPUB; USPAT	OR	ON	2005/05/13 18:02
S11	3	"5356474".URPN.	USPAT	OR	ON	2003/09/26 16:13
S12	22	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (((wash\$3 clean\$3) with (solution fluid)) same (dry\$3 heat\$3) same (etch\$3 deposit\$3 coat\$3))	US-PGPUB; USPAT	OR	ON	2003/09/26 16:34
S13	0	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (brush\$3 same rins\$3 same ultrasonic\$3)	US-PGPUB; USPAT	OR	ON	2003/09/26 16:20
S14	148	brush\$3 same rins\$3 same ultrasonic\$3	US-PGPUB; USPAT	OR	ON	2003/09/26 16:20
S15	3	(brush\$3 same rins\$3 same ultrasonic\$3) and ("118"/\$.ccls. 156/345.\$.ccls.)	US-PGPUB; USPAT	OR	ON	2003/09/26 16:21
S16	11	("1289507"   "3294576"   "3367791"   "3429741"   "3473955"   "3535157"   "3589975"   "3756196"   "4004045"   "4114563"   "4154193").PN:	USPAT	OR	ON	2003/09/26 16:26
S17	1	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (air with knife with (plural\$3 multiple))	US-PGPUB; USPAT	OR	ON	2003/09/26 16:36
S18	39	("118"/\$.ccls. 156/345.\$.ccls.) and (air with knife with (plural\$3 multiple))	US-PGPUB; USPAT	OR	ON	2003/09/26 16:36
S19	0	(c23c016\$.ipc.) and (air with knife with (plural\$3 multiple))	EPO; JPO; DERWENT	OR	ON	2003/09/26 16:38
S20	26	"4370356".URPN.	USPAT	OR	ON	2003/09/26 16:36
S21	1	(c23c016\$.ipc.) and (air with knife )	EPO; JPO; DERWENT	OR	ON	2003/09/26 18:38
S22	48	(air with knife with (plural\$3 multiple))	EPO; JPO; DERWENT	OR	ON	2003/09/26 16:47
S23	0	( (air with knife with (ion\$5))) and ( (air with knife with (heat\$3)))	EPO; JPO; DERWENT	OR	ON	2003/09/26 16:47
S24	13	(air with knife with (ion\$5))	EPO; JPO; DERWENT	OR	ON	2003/09/26 16:50
S25	0	( (air with knife with (ion\$5))) and (((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.)	US-PGPUB; USPAT	OR	ON	2003/09/26 16:51

S26~	3	( (air with knife with (ion\$5)) and ("118"/\$.ccls. 156/345.\$.ccls.)	US-PGPUB; USPAT	OR	ON	2003/09/26 16:51
S27	142	(air with knife with (heat\$3))	EPO; JPO; DERWENT	OR	ON	2003/09/26 16:57
S28	1	("4017982").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2003/09/26 16:57
S29	212	(((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (load with lock\$3 with chamber) and (clean\$3 with chamber)	US-PGPUB; USPAT	OR	ON	2003/09/26 16:59
S30	41	(((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (load with lock\$3 with chamber with heat\$3) and (clean\$3 with chamber)	US-PGPUB; USPAT	OR	ON	2003/09/26 17:12
S31	79	kondo-masataka\$.in. hayashi-katsuhiko.in. kuribe-eiji.in.	US-PGPUB; USPAT	OR	ON	2003/09/26 17:13
S32	17	(kondo-masataka\$.in. hayashi-katsuhiko.in. kuribe-eiji.in.) and (clean\$3 wash\$3 rins\$3)	US-PGPUB; USPAT	OR	ON	2003/09/26 17:19
S33	3	(("6103442") or ("5587226") or ("5501744")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2003/09/26 17:19
S34	2	("10209477").PN.	USOCR; JPO; DERWENT	OR	OFF	2003/09/26 17:20
S35	60	(air with knife with (ion\$5))	US-PGPUB; USPAT	OR	ON	2003/09/26 18:16
S36	611	(c23c016\$.ipc.) and ((film layer coat\$3) and ((material process) with gas ) and (inert with gas))	EPO; JPO; DERWENT	OR	ON	2003/09/26 18:39
S37	69	(c23c016\$.ipc.) and ((film layer coat\$3) and ((material process) with gas ) and (inert with gas) and pipe)	EPO; JPO; DERWENT	OR	ON	2003/09/26 18:39
S38	22	(c23c016\$.ipc.) and ((film layer coat\$3) and ((material process) with gas ) and (inert with gas) and pipe and plasma)	EPO; JPO; DERWENT	OR	ON	2003/09/26 18:39
S42	306	(air with knife with angl\$3)	US-PGPUB; USPAT	OR	ON	2005/05/13 17:31
S43	44	(air with knife with angl\$3) same (substrate wafer semiconductor workpiece)	US-PGPUB; USPAT	OR	ON	2005/05/13 17:32
S44	1	("3935041").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/13 17:35
S45	5	("5762749").URPN.	USPAT	OR	ON	2005/05/13 17:36
S46	2	("4077137"   "5115926").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/13 17:40
S47	2	("6073369").URPN.	USPAT	OR	ON	2005/05/13 17:41
S48	6	("4408400"   "4779355"   "5068977"   "5147690"   "5212877"   "6158141").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/13 17:44
S49	10	("4832759"   "5083226"   "5171996"   "5266141"   "5372312"   "5419733"   "5498444"   "5529829"   "5730637"   "5760502").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/13 17:47
S50	26	(((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and ((wash\$3 clean\$3) same (dry\$3 heat\$3) same (etch\$3 deposit\$3 coat\$3))) and 118/718.ccls.	US-PGPUB; USPAT	OR	ON	2005/05/13 18:02